Build Up HDI (Standard)

HDI08_1+6+1_1,20_35_engl

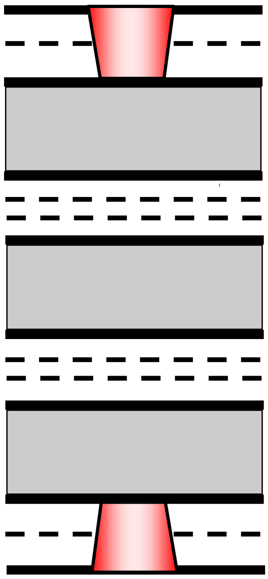
8 - Layers

Core: 0,20 mm Cu 35/35 µm

WE-Articel No.:

1 + 6 + 1

Customer:



layer description: Customer	layer description: WE	configuration	Raw-Material	CU	PREPREG	Final Thickness [µm]	Customer requirements [µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	60	
	2			35 µm		33	
			0,200 mm			200	
	3			35 µm		33	
					2 x 1080	124	
	4			35 µm		33	
			0,200 mm			200	
	5			35 µm		33	
					2 x 1080	124	
	6			35 µm		33	
			0,200 mm			200	
	7			35 µm		33	
					1 x 1080	60	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1190

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	**1,20**	+/-	0,09	mm		Date:	Engineer:
thickness with electro plated Cu:	1,29	+/-	0,12	mm			
total thickness with soldermask	1,35	+/-	0,14	mm			
customer requirement		+/-		mm	point:		

prepared: on	by	checked: on	by	approved: on	by	revision	
25.04.2006	**S. Keller**	04.05.2006	M.Kress	25.04.2006	R. Schönholz	00	page: 3+